



Material Content Data Sheet



Sales Product Name				SPD04N80C3		Issued		16. March 2016	
MA#				MA000458326					
Package				PG-TO252-3-311		Weight*		315.70 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.894	1.23	1.23	12333	12333	
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		454		
	inorganic material	phosphorus	7723-14-0	0.043	0.01		136		
	non noble metal	copper	7440-50-8	143.098	45.33	45.39	453278	453868	
wire	non noble metal	aluminium	7429-90-5	5.329	1.69	1.69	16880	16880	
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.915	0.61		6065		
	plastics	brominated resin	-	2.051	0.65		6498		
	organic material	carbon black	1333-86-4	2.188	0.69		6931		
	plastics	epoxy resin	-	18.463	5.85		58484		
	inorganic material	silicondioxide	60676-86-0	112.147	35.52	43.32	355239	433217	
leadfinish	non noble metal	tin	7440-31-5	3.787	1.20	1.20	11995	11995	
plating	non noble metal	nickel	7440-02-0	0.086	0.03		274		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	275	
solder	noble metal	silver	7440-22-4	0.084	0.03		265		
	non noble metal	tin	7440-31-5	0.067	0.02		212		
	non noble metal	lead	7439-92-1	3.198	1.01	1.06	10129	10606	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		61		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.07	6.08	60747	60826	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com